

## **Quarterly Reliability Monitoring Results**

## Quarters: Q1/2022 to Q4/2023

Based on structural similarity

| Supplier Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test |   | User Part Number  |                                   |           |            |           |  |  |
|--|---|---|-----------------------------------|-----------|------------|-----------|--|--|
|  |   | BZX384-A22-Q  |                                   |           |            |           |  |  |
|  |   | Part Description  |                                   |           |            |           |  |  |
|  |   | Nexperia DHAM Zener   |                                   |           |            |           |  |  |
|  |   | SMD package   |                                   |           |            |           |  |  |
|  |   | Test Conditions   | Duration                          | # Lots    | # Quantity | # Rejects |  |  |
|  | <b>TEST</b> Pre- and Post-Stress                        |   |                                   |           |            |           |  |  |
| # E1   | Electrical Test   | Tamb = 25 °C  | N/A                               | see below | all parts  | see below |  |  |
| # A1   | <b>PC</b> Preconditioning                               | JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85% Reflow soldering                   | 24 hours<br>168 hours<br>3 cycles | 1514      | 64430      | 0         |  |  |
| # B1   | HTRB  | MIL-STD-750-1<br>M1038 Method A<br>Tj = Tjmax, VR = 80 % of rated reverse<br>voltage          | 1000 hours                        | 250       | 11400      | 0         |  |  |
| # B1b  | SSOP<br>Steady State Operational                        | MIL-STD-750-1<br>M1038 Method B<br>Tj = Tjmax, Iz = 100% of max. datasheet<br>reverse current | 1000 hours                        | 44        | 1920       | 0         |  |  |
| # A4   | TC<br>Temperature Cycling                               | JESD22-A104<br>-65 °C to Tjmax, not to exceed 150°C   | 1000 cycles                       | 311       | 14080      | 0         |  |  |
| # A3 <b>or</b>   | UHAST<br>Unbiased HAST                                  | JESD22-A118<br>Tamb = 130 °C, RH = 85 %<br>JESD22-A102  | —96 hours                         | 311       | 14080      | 0         |  |  |
| # A3 alt   | <b>AC</b><br>Autoclave                                  | Tamb = 121 °C, RH = 100 %<br>Pressure = 205 kPa (29.7 psia)                                   |                                   |           |            |           |  |  |
| # A2 - It  | H3TRB<br>High Humidity High<br>Temperature Reverse Bias | JESD22-A101<br>Tamb = 85 °C, RH = 85%, VR = 80 % of   | 1000 haves                        | 211       | 14000      | 0         |  |  |
| # A2 alt   | IOL   | MIL-STD-750 Method 1037 ton = toff, devices powered to insure ΔTj =                           | 1000 hours                        | 311       | 14080      | 0         |  |  |
| # A5   | Intermittent Operating Life                             | , .   | 1000 hours                        | 312       | 14120      | 0         |  |  |
| # C8   | <b>RSH</b><br>Resistance to Solder Heat                 | JESD22-A111<br>260 °C ± 5 °C  | 10 s                              | 269       | 8070       | 0         |  |  |
| # C10  | <b>SD</b><br>Solderability                              | J-STD-002   |                                   | 19        | 6660       | 0         |  |  |

<sup>[1]</sup> The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab | Technology | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|-----------|------------|----------|---------|--------------------|------------|
| Nexperia  |            |          |         |                    |            |
| DHAM      | Zener      | 11400    | 0       | 0,37               | 2,68E+09   |

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